2SD1994A

Silicon NPN epitaxial planer type

For low-frequency power amplification and driver amplification Complementary to 2SB1322A

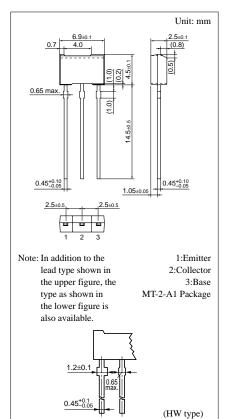
Features

- Low collector to emitter saturation voltage V_{CE(sat)}.
- Output of 2 to 3W is obtained with a complementary pair with 2SB1322A.
- Allowing supply with the radial taping.

Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Collector to base voltage	V_{CBO}	60	V
Collector to emitter voltage	V_{CEO}	50	V
Emitter to base voltage	$V_{\rm EBO}$	5	V
Peak collector current	I_{CP}	1.5	A
Collector current	I_{C}	1	A
Collector power dissipation	${P_C}^*$	1	W
Junction temperature	T_{j}	150	°C
Storage temperature	T_{stg}	−55 ~ +150	°C

 $^{^{\}ast}$ Printed circuit board: Copper foil area of 1cm² or more, and the board thickness of 1.7mm for the collector portion



Electrical Characteristics (Ta=25°C)

Parameter	Symbol	Conditions	min	typ	max	Unit
Collector cutoff current	I_{CBO}	$V_{CB} = 20V, I_{E} = 0$			0.1	μΑ
Collector to base voltage	V _{CBO}	$I_{\rm C} = 10\mu A, I_{\rm E} = 0$				V
Collector to emitter voltage	V _{CEO}	$I_C = 2mA, I_B = 0$ 50				V
Emitter to base voltage	V _{EBO}	$I_{\rm E} = 10 \mu {\rm A}, I_{\rm C} = 0$	5			V
Forward current transfer ratio	h _{FE1} *1	$V_{CE} = 10V, I_{C} = 500 \text{mA}^{*2}$	85	160	340	
	h _{FE2}	$V_{CE} = 5V, I_{C} = 1A^{*2}$	50	100		
Collector to emitter saturation voltage	V _{CE(sat)}	$I_C = 500 \text{mA}, I_B = 50 \text{mA}^{*2}$		0.2	0.4	V
Base to emitter saturation voltage	V _{BE(sat)}	$I_C = 500 \text{mA}, I_B = 50 \text{mA}^{*2}$		0.85	1.2	V
Transition frequency	f_{T}	$V_{CB} = 10V, I_E = -50mA, f = 200MHz$		200		MHz
Collector output capacitance	C _{ob}	$V_{CB} = 10V, I_{E} = 0, f = 1MHz$		11	20	pF

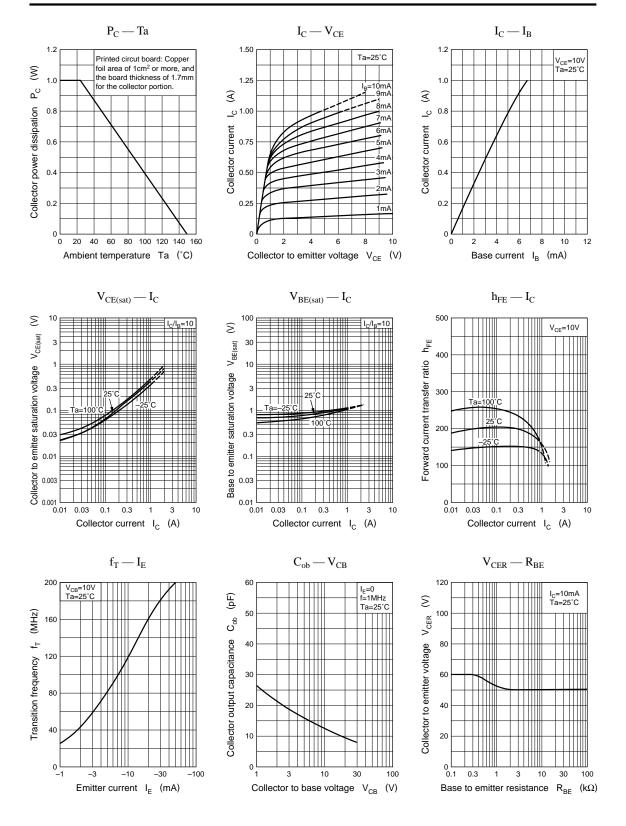
^{*2} Pulse measurement

^{*1}hFE1 Rank classification

Rank	Q	R	S
h_{FE1}	85 ~ 170	120 ~ 240	170 ~ 340

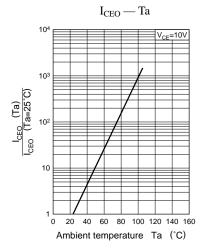
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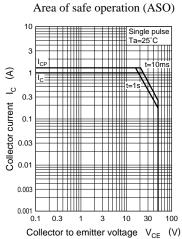
Transistor 2SD1994A



Panasonic 655

Transistor 2SD1994A





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